LM117/LM317A/LM317 3-Terminal Adjustable Regulator

Check for Samples: LM117, LM317-N

FEATURES

- **Guaranteed 1% output voltage tolerance (LM317A)**
- **Guaranteed max. 0.01%/V line regulation (LM317A)**
- **Guaranteed max. 0.3% load regulation (LM117)**
- **Guaranteed 1.5A output current**
- **Adjustable output down to 1.2V**
- **Current limit constant with temperature**
- **P^+ Product Enhancement tested**
- **80 dB ripple rejection**
- **Output is short-circuit protected**

DESCRIPTION

The LM117 series of adjustable 3-terminal positive voltage regulators is capable of supplying in excess of 1.5A over a 1.2V to 37V output range. They are exceptionally easy to use and require only two external resistors to set the output voltage. Further, both line and load regulation are better than standard fixed regulators. Also, the LM117 is packaged in standard transistor packages which are easily mounted and handled.

In addition to higher performance than fixed regulators, the LM117 series offers full overload protection available only in IC's. Included on the chip are current limit, thermal overload protection and safe area protection. All overload protection circuitry remains fully functional even if the adjustment terminal is disconnected.

Normally, no capacitors are needed unless the device is situated more than 6 inches from the input filter capacitors in which case an input bypass is needed. An optional output capacitor can be added to improve transient response. The adjustment terminal can be bypassed to achieve very high ripple rejection ratios which are difficult to achieve with standard 3-terminal regulators.

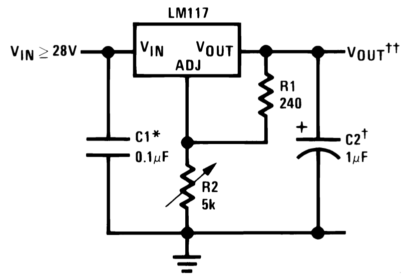
Besides replacing fixed regulators, the LM117 is useful in a wide variety of other applications. Since the regulator is “floating” and sees only the input-to-output differential voltage, supplies of several hundred volts can be regulated as long as the maximum input to output differential is not exceeded, i.e., avoid short-circuiting the output.

Also, it makes an especially simple adjustable switching regulator, a programmable output regulator, or by connecting a fixed resistor between the adjustment pin and output, the LM117 can be used as a precision current regulator. Supplies with electronic shutdown can be achieved by clamping the adjustment terminal to ground which programs the output to 1.2V where most loads draw little current.

For applications requiring greater output current, see LM150 series (3A) and LM138 series (5A) data sheets. For the negative complement, see LM137 series data sheet.

Typical Applications

Figure 1. 1.2V–25V Adjustable Regulator



Full output current not available at high input-output voltages

*Needed if device is more than 6 inches from filter capacitors.

†Optional—improves transient response. Output capacitors in the range of 1μF to 1000μF of aluminum or tantalum electrolytic are commonly used to provide improved output impedance and rejection of transients.

$$††V_{OUT} = 1.25V\left(1 + \frac{R2}{R1}\right) + I_{ADJ}(R_2)$$

Table 1. LM117/LM317A/LM317 Package Options

Part Number	Suffix	Package	Output Current
LM117, LM317	K	TO-3	1.5A
LM317A, LM317	T	TO-220	1.5A
LM317	S	TO-263	1.5A
LM317A, LM317	EMP	SOT-223	1.0A
LM117, LM317A, LM317	H	TO-39	0.5A
LM117	E	LCC	0.5A
LM317A, LM317	MDT	TO-252	0.5A

SOT-223 vs. TO-252 (D-Pak) Packages

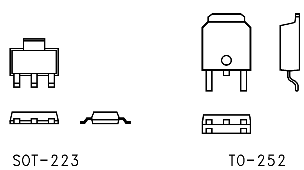
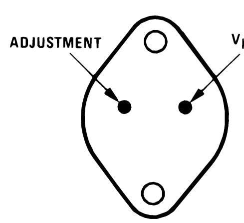


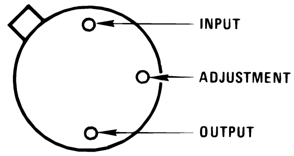
Figure 2. Scale 1:1

Connection Diagrams



CASE IS OUTPUT

Figure 3. TO-3 (K)
Metal Can Package



CASE IS OUTPUT

Figure 4. TO-39 (H) Metal Can Package

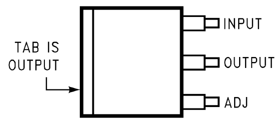


Figure 5. TO-263 (S) Surface-Mount Package

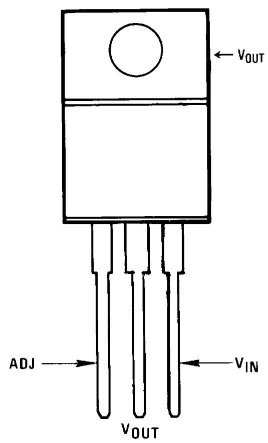


Figure 6. TO-220 (T) Plastic Package

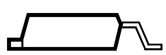


Figure 7. TO-263 (S) Surface-Mount Package

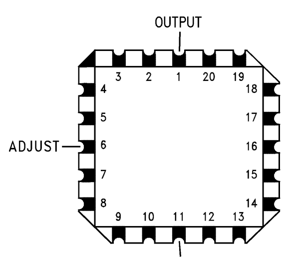


Figure 8. Ceramic Leadless Chip Carrier (E)

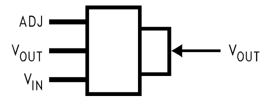


Figure 9. 4-Lead SOT-223 (EMP)

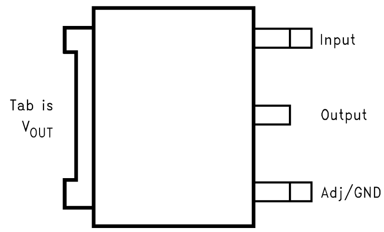


Figure 10. TO-252 (MDT)

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings [1]

Power Dissipation	Internally Limited
Input-Output Voltage Differential	+40V, −0.3V
Storage Temperature	−65°C to +150°C
Lead Temperature	
Metal Package (Soldering, 10 seconds)	300°C
Plastic Package (Soldering, 4 seconds)	260°C
ESD Tolerance [2]	3 kV

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed.
(2) Human body model, 100 pF discharged through a 1.5 kΩ resistor.

Operating Temperature Range

LM117	$-55°C \le T_J \le +150°C$
LM317A	$-40°C \le T_J \le +125°C$
LM317	$0°C \le T_J \le +125°C$

Preconditioning

Thermal Limit Burn-In	All Devices 100%

LM117 Electrical Characteristics(1)

Specifications with standard type face are for T_J = 25°C, and those with **boldface type** apply over **full Operating Temperature Range**. Unless otherwise specified, $V_{IN} - V_{OUT}$ = 5V, and I_{OUT} = 10 mA.

Parameter	Conditions	LM117 (2)			
		Min	Typ	Max	Units
Reference Voltage	3V ≤ ($V_{IN} - V_{OUT}$) ≤ 40V, 10 mA ≤ I_{OUT} ≤ I_{MAX} (1)	**1.20**	**1.25**	**1.30**	V
Line Regulation	3V ≤ ($V_{IN} - V_{OUT}$) ≤ 40V (3)		0.01 **0.02**	0.02 **0.05**	%/V
Load Regulation	10 mA ≤ I_{OUT} ≤ I_{MAX} (1) (3)		0.1 **0.3**	0.3 **1**	%
Thermal Regulation	20 ms Pulse		0.03	0.07	%/W
Adjustment Pin Current			**50**	**100**	μA
Adjustment Pin Current Change	10 mA ≤ I_{OUT} ≤ I_{MAX} (1) 3V ≤ ($V_{IN} - V_{OUT}$) ≤ 40V		**0.2**	**5**	μA
Temperature Stability	$T_{MIN} \le T_J \le T_{MAX}$		**1**		%
Minimum Load Current	($V_{IN} - V_{OUT}$) = 40V		**3.5**	**5**	mA
Current Limit	($V_{IN} - V_{OUT}$) ≤ 15V				
	K Package H, E Package	**1.5** **0.5**	**2.2** **0.8**	**3.4** **1.8**	A
	($V_{IN} - V_{OUT}$) = 40V				
	K Package H, E Package	0.3 0.15	0.4 0.20		A
RMS Output Noise, % of V_{OUT}	10 Hz ≤ f ≤ 10 kHz		0.003		%
Ripple Rejection Ratio	V_{OUT} = 10V, f = 120 Hz, C_{ADJ} = 0 μF		**65**		dB
	V_{OUT} = 10V, f = 120 Hz, C_{ADJ} = 10 μF	**66**	**80**		dB
Long-Term Stability	T_J = 125°C, 1000 hrs		0.3	1	%
Thermal Resistance, θ_{JC} Junction-to-Case	K (TO-3) Package H (TO-39) Package E (LCC) Package		2 21 12		°C/W
Thermal Resistance, θ_{JA} Junction-to-Ambient (No Heat Sink)	K (TO-3) Package H (TO-39) Package E (LCC) Package		39 186 88		°C/W

(1) I_{MAX} = 1.5A for the K (TO-3), T (TO-220), and S (TO-263) packages. I_{MAX} = 1.0A for the EMP (SOT-223) package. I_{MAX} = 0.5A for the H (TO-39), MDT (TO-252), and E (LCC) packages. Device power dissipation (P_D) is limited by ambient temperature (T_A), device maximum junction temperature (T_J), and package thermal resistance (θ_{JA}). The maximum allowable power dissipation at any temperature is : $P_{D(MAX)} = ((T_{J(MAX)} - T_A)/\theta_{JA})$. All Min. and Max. limits are guaranteed to National's Average Outgoing Quality Level (AOQL).
(2) Refer to RETS117H drawing for the LM117H, or the RETS117K for the LM117K military specifications.
(3) Regulation is measured at a constant junction temperature, using pulse testing with a low duty cycle. Changes in output voltage due to heating effects are covered under the specifications for thermal regulation.

LM317A and LM317 Electrical Characteristics[1]

Specifications with standard type face are for T_J = 25°C, and those with **boldface type** apply over **full Operating Temperature Range**. Unless otherwise specified, $V_{IN} - V_{OUT}$ = 5V, and I_{OUT} = 10 mA.

Parameter	Conditions	LM317A			LM317			
		Min	Typ	Max	Min	Typ	Max	Units
Reference Voltage		1.238	1.250	1.262	-	1.25	-	V
	$3V \le (V_{IN} - V_{OUT}) \le 40V$, $10 mA \le I_{OUT} \le I_{MAX}$ [1]	**1.225**	**1.250**	**1.270**	**1.20**	**1.25**	**1.30**	V
Line Regulation	$3V \le (V_{IN} - V_{OUT}) \le 40V$ [2]		0.005 **0.01**	0.01 **0.02**		0.01 **0.02**	0.04 **0.07**	%/V
Load Regulation	$10 mA \le I_{OUT} \le I_{MAX}$ [1] [2]		0.1 **0.3**	0.5 **1**		0.1 **0.3**	0.5 **1.5**	%
Thermal Regulation	20 ms Pulse		0.04	0.07		0.04	0.07	%/W
Adjustment Pin Current			**50**	**100**		**50**	**100**	μA
Adjustment Pin Current Change	$10 mA \le I_{OUT} \le I_{MAX}$ [1] $3V \le (V_{IN} - V_{OUT}) \le 40V$		**0.2**	**5**		**0.2**	**5**	μA
Temperature Stability	$T_{MIN} \le T_J \le T_{MAX}$		**1**			**1**		%
Minimum Load Current	$(V_{IN} - V_{OUT})$ = 40V		**3.5**	**10**		**3.5**	**10**	mA
Current Limit	$(V_{IN} - V_{OUT}) \le 15V$							
	K, S Packages EMP, T Packages H, MDT Packages	- **1.5** **0.5**	- **2.2** **0.8**	- **3.4** **1.8**	**1.5** **1.5** **0.5**	**2.2** **2.2** **0.8**	**3.4** **3.4** **1.8**	A
	$(V_{IN} - V_{OUT})$ = 40V							
	K, S Packages EMP, T Packages H, MDT Packages	- 0.112 0.075	- 0.30 0.20		0.15 0.112 0.075	0.40 0.30 0.20		A
RMS Output Noise, % of V_{OUT}	10 Hz ≤ f ≤ 10 kHz		0.003			0.003		%
Ripple Rejection Ratio	V_{OUT} = 10V, f = 120 Hz, C_{ADJ} = 0 μF		**65**			**65**		dB
	V_{OUT} = 10V, f = 120 Hz, C_{ADJ} = 10 μF	**66**	**80**		**66**	**80**		dB
Long-Term Stability	T_J = 125°C, 1000 hrs		0.3	1		0.3	1	%
Thermal Resistance, θ_{JC} Junction-to-Case	K (TO-3) Package T (TO-220) Package S (TO-263) Package EMP (SOT-223) Package H (TO-39) Package MDT (TO-252) Package		- 4 - 23.5 21 12			2 4 4 23.5 21 12		°C/W
Thermal Resistance, θ_{JA} Junction-to-Ambient (No Heat Sink)	K (TO-3) Package T (TO-220) Package S (TO-263) Package [3] EMP (SOT-223) Package [3] H (TO-39) Package MDT (TO-252) Package [3]		- 50 - 140 186 103			39 50 50 140 186 103		°C/W

(1) I_{MAX} = 1.5A for the K (TO-3), T (TO-220), and S (TO-263) packages. I_{MAX} = 1.0A for the EMP (SOT-223) package. I_{MAX} = 0.5A for the H (TO-39), MDT (TO-252), and E (LCC) packages. Device power dissipation (P_D) is limited by ambient temperature (T_A), device maximum junction temperature (T_J), and package thermal resistance (θ_{JA}). The maximum allowable power dissipation at any temperature is : $P_{D(MAX)} = ((T_{J(MAX)} - T_A)/\theta_{JA})$. All Min. and Max. limits are guaranteed to National's Average Outgoing Quality Level (AOQL).

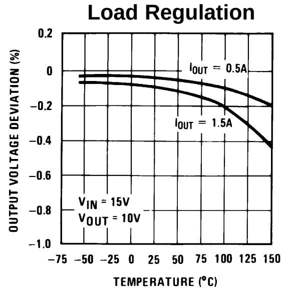
(2) Regulation is measured at a constant junction temperature, using pulse testing with a low duty cycle. Changes in output voltage due to heating effects are covered under the specifications for thermal regulation.

(3) When surface mount packages are used (TO-263, SOT-223, TO-252), the junction to ambient thermal resistance can be reduced by increasing the PC board copper area that is thermally connected to the package. See the Applications Hints section for heatsink techniques.

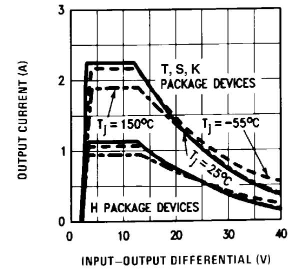
Typical Performance Characteristics

Output Capacitor = 0 µF unless otherwise noted

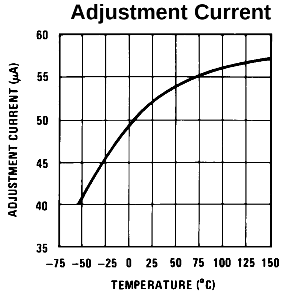
Load Regulation



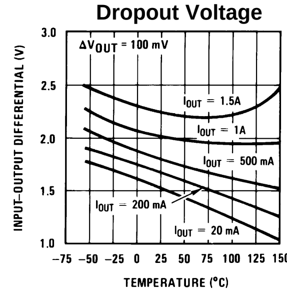
Current Limit



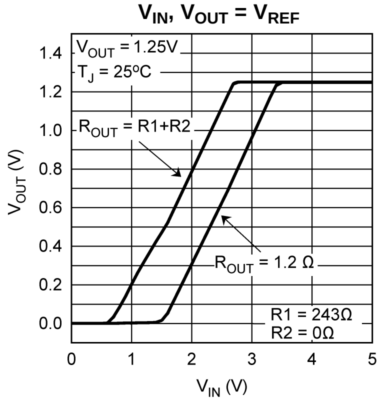
Adjustment Current



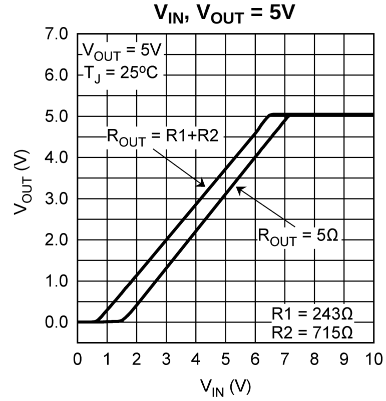
Dropout Voltage



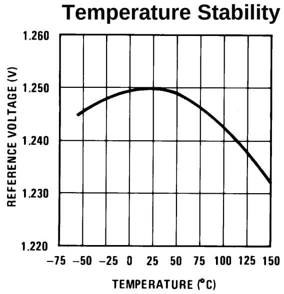
V_{OUT} vs V_{IN}, V_{OUT} = V_{REF}



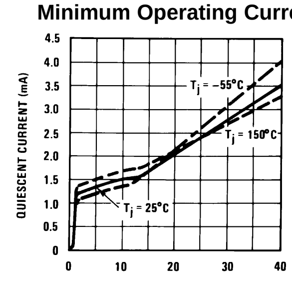
V_{OUT} vs V_{IN}, V_{OUT} = 5V



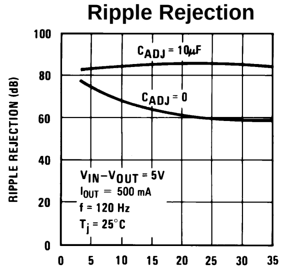
Temperature Stability



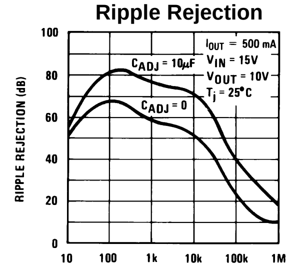
Minimum Operating Current



Ripple Rejection



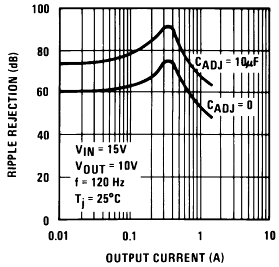
Ripple Rejection



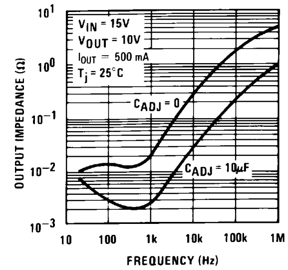
Typical Performance Characteristics (continued)

Output Capacitor = 0 μF unless otherwise noted

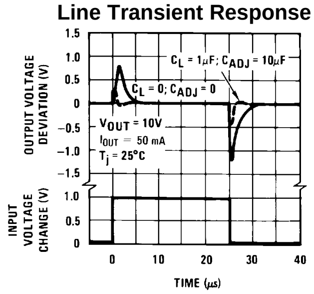
Ripple Rejection



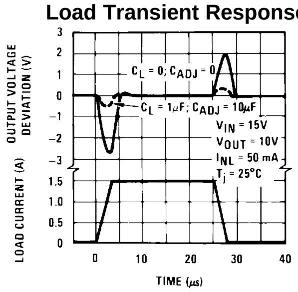
Output Impedance



Line Transient Response



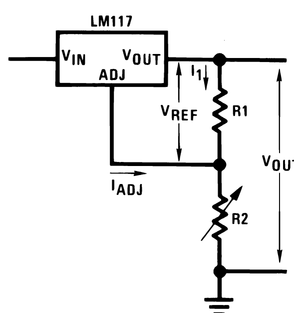
Load Transient Response



Application Hints

In operation, the LM117 develops a nominal 1.25V reference voltage, V_{REF}, between the output and adjustment terminal. The reference voltage is impressed across program resistor R1 and, since the voltage is constant, a constant current I_1 then flows through the output set resistor R2, giving an output voltage of

$$V_{OUT} = V_{REF}\left(1 + \frac{R2}{R1}\right) + I_{ADJ}R2 \quad (1)$$



Since the 100μA current from the adjustment terminal represents an error term, the LM117 was designed to minimize I_{ADJ} and make it very constant with line and load changes. To do this, all quiescent operating current is returned to the output establishing a minimum load current requirement. If there is insufficient load on the output, the output will rise.

EXTERNAL CAPACITORS

An input bypass capacitor is recommended. A 0.1μF disc or 1μF solid tantalum on the input is suitable input bypassing for almost all applications. The device is more sensitive to the absence of input bypassing when adjustment or output capacitors are used but the above values will eliminate the possibility of problems.

The adjustment terminal can be bypassed to ground on the LM117 to improve ripple rejection. This bypass capacitor prevents ripple from being amplified as the output voltage is increased. With a 10 μF bypass capacitor 80dB ripple rejection is obtainable at any output level. Increases over 10 μF do not appreciably improve the ripple rejection at frequencies above 120Hz. If the bypass capacitor is used, it is sometimes necessary to include protection diodes to prevent the capacitor from discharging through internal low current paths and damaging the device.

In general, the best type of capacitors to use is solid tantalum. Solid tantalum capacitors have low impedance even at high frequencies. Depending upon capacitor construction, it takes about 25 μF in aluminum electrolytic to equal 1μF solid tantalum at high frequencies. Ceramic capacitors are also good at high frequencies; but some types have a large decrease in capacitance at frequencies around 0.5 MHz. For this reason, 0.01 μF disc may seem to work better than a 0.1 μF disc as a bypass.

Although the LM117 is stable with no output capacitors, like any feedback circuit, certain values of external capacitance can cause excessive ringing. This occurs with values between 500 pF and 5000 pF. A 1 μF solid tantalum (or 25 μF aluminum electrolytic) on the output swamps this effect and insures stability. Any increase of the load capacitance larger than 10 μF will merely improve the loop stability and output impedance.

LOAD REGULATION

The LM117 is capable of providing extremely good load regulation but a few precautions are needed to obtain maximum performance. The current set resistor connected between the adjustment terminal and the output terminal (usually 240Ω) should be tied directly to the output (case) of the regulator rather than near the load. This eliminates line drops from appearing effectively in series with the reference and degrading regulation. For example, a 15V regulator with 0.05Ω resistance between the regulator and load will have a load regulation due to line resistance of 0.05Ω × I_L. If the set resistor is connected near the load the effective line resistance will be 0.05Ω (1 + R2/R1) or in this case, 11.5 times worse.

Figure 11 shows the effect of resistance between the regulator and 240Ω set resistor.

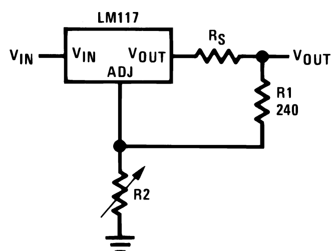


Figure 11. Regulator with Line Resistance in Output Lead

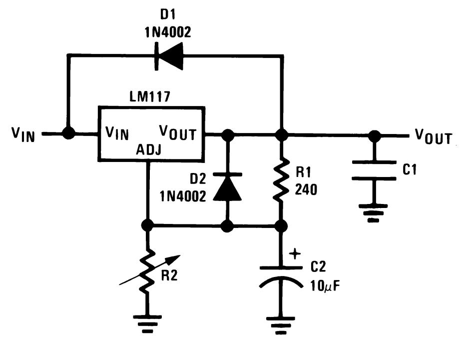
With the TO-3 package, it is easy to minimize the resistance from the case to the set resistor, by using two separate leads to the case. However, with the TO-39 package, care should be taken to minimize the wire length of the output lead. The ground of R2 can be returned near the ground of the load to provide remote ground sensing and improve load regulation.

PROTECTION DIODES

When external capacitors are used with any IC regulator it is sometimes necessary to add protection diodes to prevent the capacitors from discharging through low current points into the regulator. Most 10 μF capacitors have low enough internal series resistance to deliver 20A spikes when shorted. Although the surge is short, there is enough energy to damage parts of the IC.

When an output capacitor is connected to a regulator and the input is shorted, the output capacitor will discharge into the output of the regulator. The discharge current depends on the value of the capacitor, the output voltage of the regulator, and the rate of decrease of V_{IN}. In the LM117, this discharge path is through a large junction that is able to sustain 15A surge with no problem. This is not true of other types of positive regulators. For output capacitors of 25 μF or less, there is no need to use diodes.

The bypass capacitor on the adjustment terminal can discharge through a low current junction. Discharge occurs when *either* the input, or the output, is shorted. Internal to the LM117 is a 50Ω resistor which limits the peak discharge current. No protection is needed for output voltages of 25V or less and 10 μF capacitance. *Figure 12* shows an LM117 with protection diodes included for use with outputs greater than 25V and high values of output capacitance.



$$V_{OUT} = 1.25V\left(1 + \frac{R2}{R1}\right) + I_{ADJ}R2$$

D1 protects against C1
D2 protects against C2

Figure 12. Regulator with Protection Diodes

HEATSINK REQUIREMENTS

The LM317 regulators have internal thermal shutdown to protect the device from over-heating. Under all operating conditions, the junction temperature of the LM317 should not exceed the rated maximum junction temperature (T_J) of 150°C for the LM117, or 125°C for the LM317A and LM317. A heatsink may be required depending on the maximum device power dissipation and the maximum ambient temperature of the application. To determine if a heatsink is needed, the power dissipated by the regulator, P_D, must be calculated:

$$P_D = ((V_{IN} - V_{OUT}) \times I_L) + (V_{IN} \times I_G) \quad (2)$$

Figure 13 shows the voltage and currents which are present in the circuit.

The next parameter which must be calculated is the maximum allowable temperature rise, $T_{R(MAX)}$:

$$T_{R(MAX)} = T_{J(MAX)} - T_{A(MAX)} \quad (3)$$

where $T_{J(MAX)}$ is the maximum allowable junction temperature (150°C for the LM117, or 125°C for the LM317A/LM317), and $T_{A(MAX)}$ is the maximum ambient temperature which will be encountered in the application.

Using the calculated values for $T_{R(MAX)}$ and P_D, the maximum allowable value for the junction-to-ambient thermal resistance (θ_{JA}) can be calculated:

$$\theta_{JA} = (T_{R(MAX)} / P_D) \quad (4)$$

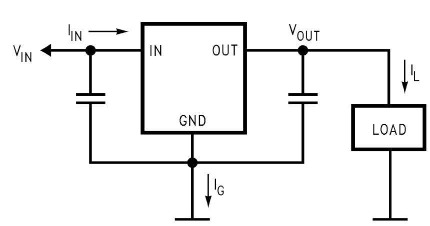


Figure 13. Power Dissipation Diagram

If the calculated maximum allowable thermal resistance is higher than the actual package rating, then no additional work is needed. If the calculated maximum allowable thermal resistance is lower than the actual package rating either the power dissipation (P_D) needs to be reduced, the maximum ambient temperature $T_{A(MAX)}$ needs to be reduced, the thermal resistance (θ_{JA}) must be lowered by adding a heatsink, or some combination of these.

If a heatsink is needed, the value can be calculated from the formula:

$$\theta_{HA} \leq (\theta_{JA} - (\theta_{CH} + \theta_{JC})) \quad (5)$$

where (θ_{CH} is the thermal resistance of the contact area between the device case and the heatsink surface, and θ_{JC} is thermal resistance from the junction of the die to surface of the package case.

When a value for $\theta_{(H-A)}$ is found using the equation shown, a heatsink must be selected that has a value that is less than, or equal to, this number.

The $\theta_{(H-A)}$ rating is specified numerically by the heatsink manufacturer in the catalog, or shown in a curve that plots temperature rise vs power dissipation for the heatsink.

HEATSINKING SURFACE MOUNT PACKAGES

The TO-263 (S), SOT-223 (EMP) and TO-252 (MDT) packages use a copper plane on the PCB and the PCB itself as a heatsink. To optimize the heat sinking ability of the plane and PCB, solder the tab of the package to the plane.

HEATSINKING THE SOT-223 PACKAGE

Figure 14 and Figure 15 show the information for the SOT-223 package. Figure 15 assumes a $\theta_{(J-A)}$ of 74°C/W for 1 ounce copper and 51°C/W for 2 ounce copper and a maximum junction temperature of 125°C. Please see AN-1028 for thermal enhancement techniques to be used with SOT-223 and TO-252 packages.

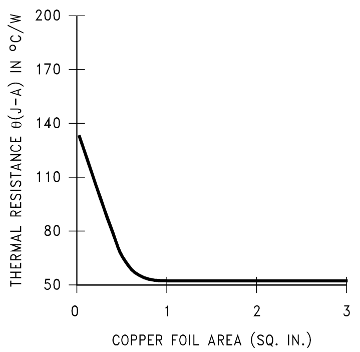


Figure 14. $\theta_{(J-A)}$ vs Copper (2 ounce) Area for the SOT-223 Package

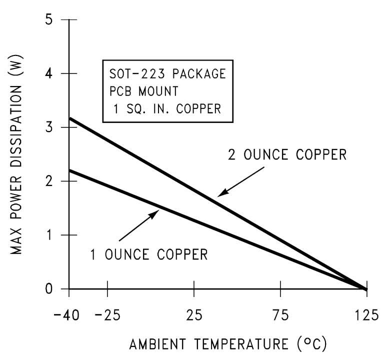


Figure 15. Maximum Power Dissipation vs T_{AMB} for the SOT-223 Package

HEATSINKING THE TO-263 PACKAGE

Figure 16 shows for the TO-263 the measured values of $\theta_{(J-A)}$ for different copper area sizes using a typical PCB with 1 ounce copper and no solder mask over the copper area used for heatsinking.

As shown in Figure 16, increasing the copper area beyond 1 square inch produces very little improvement. It should also be observed that the minimum value of $\theta_{(J-A)}$ for the TO-263 package mounted to a PCB is 32°C/W.

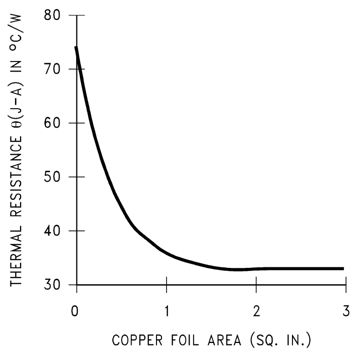


Figure 16. $\theta_{(J-A)}$ vs Copper (1 ounce) Area for the TO-263 Package

As a design aid, Figure 17 shows the maximum allowable power dissipation compared to ambient temperature for the TO-263 device (assuming $\theta_{(J-A)}$ is 35°C/W and the maximum junction temperature is 125°C).

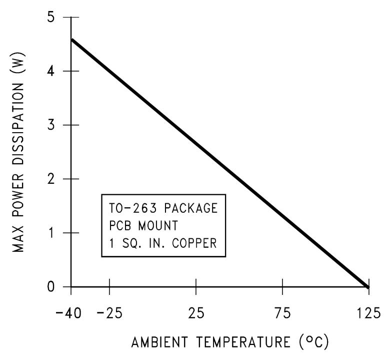


Figure 17. Maximum Power Dissipation vs T_{AMB} for the TO-263 Package

HEATSINKING THE TO-252 PACKAGE

If the maximum allowable value for θ_{JA} is found to be ≥103°C/W (Typical Rated Value) for TO-252 package, no heatsink is needed since the package alone will dissipate enough heat to satisfy these requirements. If the calculated value for θ_{JA} falls below these limits, a heatsink is required.

As a design aid, Table 2 shows the value of the θ_{JA} of TO-252 for different heatsink area. The copper patterns that we used to measure these θ_{JA}s are shown at the end of the Application Notes Section. Figure 18 reflects the same test results as what are in Table 2.

Figure 19 shows the maximum allowable power dissipation vs. ambient temperature for the TO-252 device. Figure 20 shows the maximum allowable power dissipation vs. copper area (in^2) for the TO-252 device. Please see AN-1028 for thermal enhancement techniques to be used with SOT-223 and TO-252 packages.

Table 2. θ_{JA} Different Heatsink Area

Layout	Copper Area		Thermal Resistance
	Top Side (in^2)*	Bottom Side (in^2)	(θ_{JA}°C/W) TO-252
1	0.0123	0	103
2	0.066	0	87
3	0.3	0	60

Table 2. θ_{JA} Different Heatsink Area (continued)

Layout	Copper Area		Thermal Resistance
4	0.53	0	54
5	0.76	0	52
6	1.0	0	47
7	0.066	0.2	84
8	0.066	0.4	70
9	0.066	0.6	63
10	0.066	0.8	57
11	0.066	1.0	57
12	0.066	0.066	89
13	0.175	0.175	72
14	0.284	0.284	61
15	0.392	0.392	55
16	0.5	0.5	53

NOTE

* Tab of device attached to topside of copper.

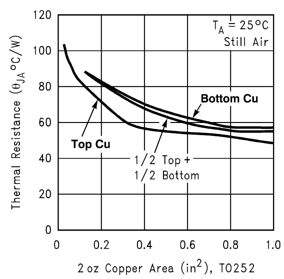


Figure 18. θ_{JA} vs 2oz Copper Area for TO-252

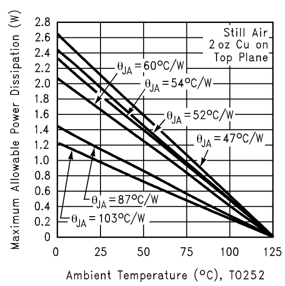


Figure 19. Maximum Allowable Power Dissipation vs. Ambient Temperature for TO-252

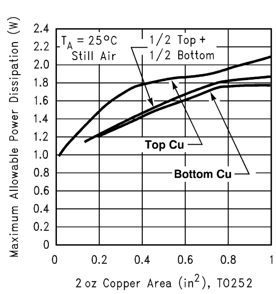


Figure 20. Maximum Allowable Power Dissipation vs. 2oz Copper Area for TO-252

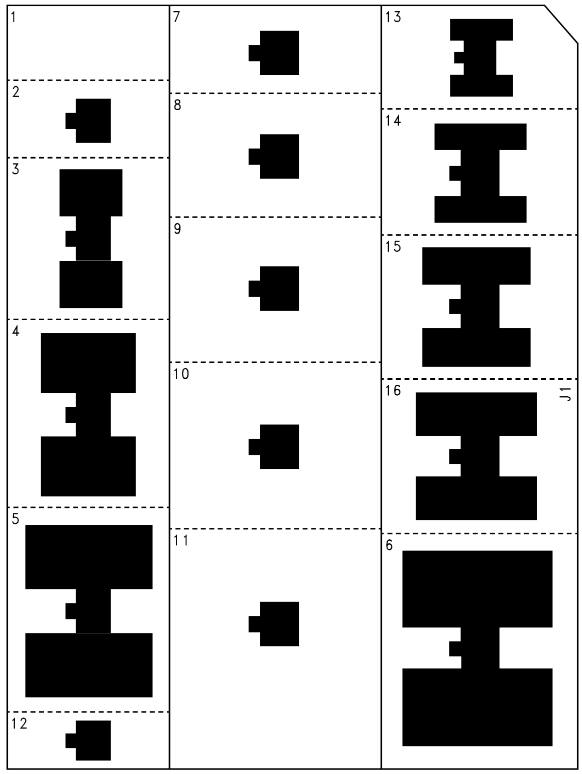


Figure 21. Top View of the Thermal Test Pattern in Actual Scale

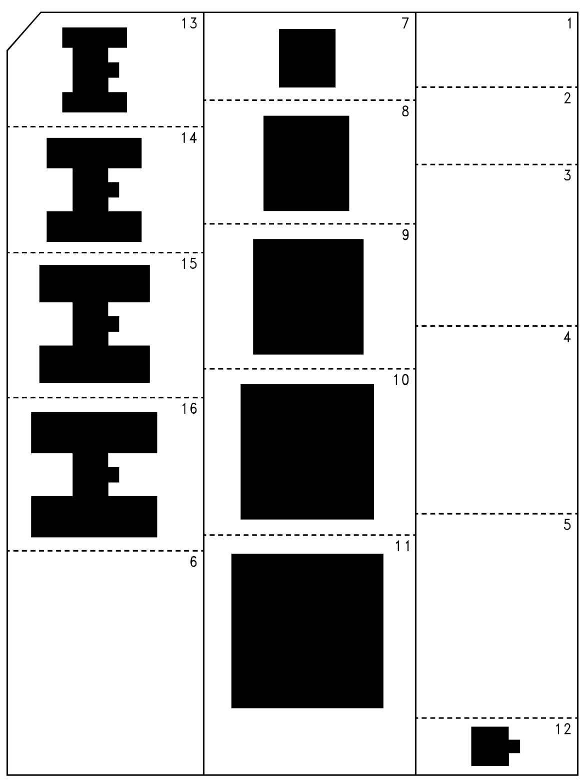
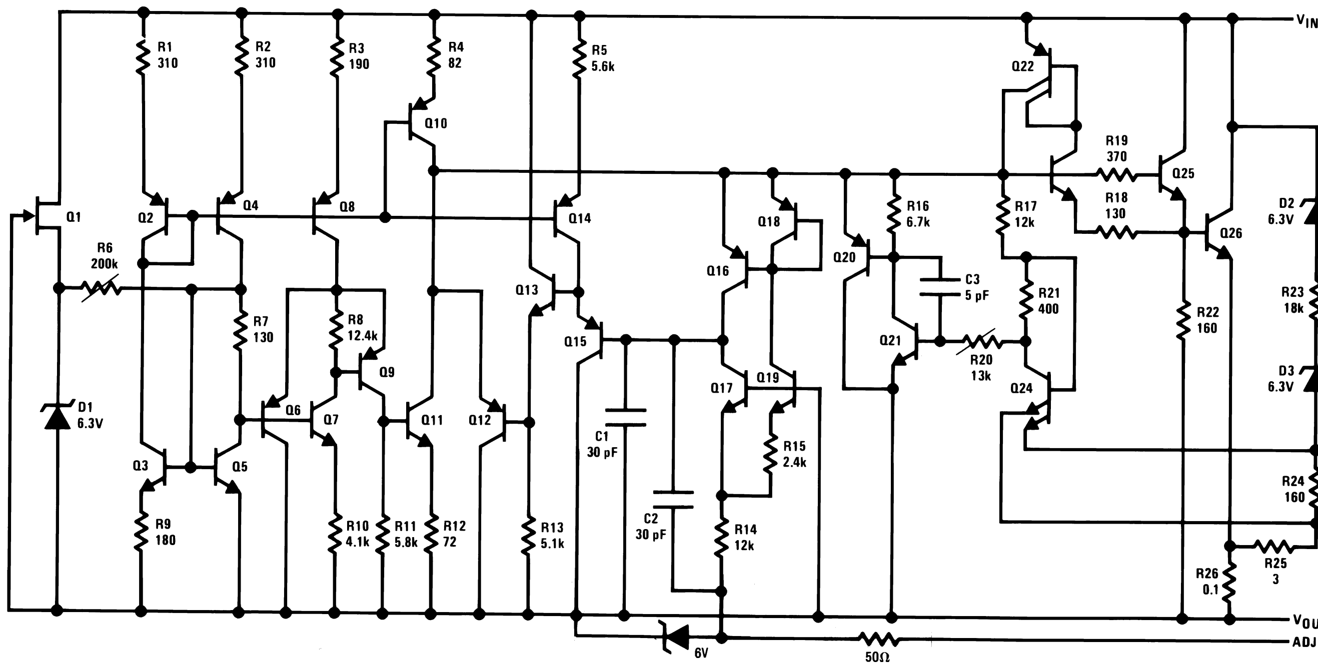


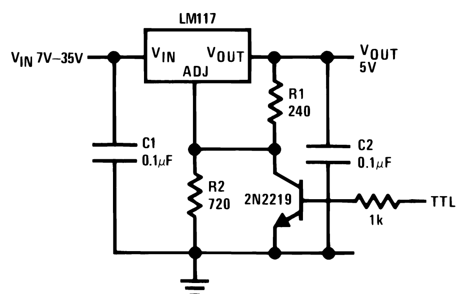
Figure 22. Bottom View of the Thermal Test Pattern in Actual Scale

Schematic Diagram



Typical Applications

Figure 23. 5V Logic Regulator with Electronic Shutdown*



*Min. output ≅ 1.2V

Figure 24. Slow Turn-On 15V Regulator

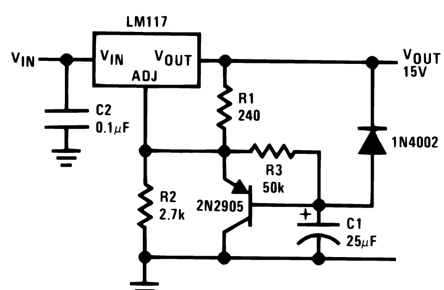
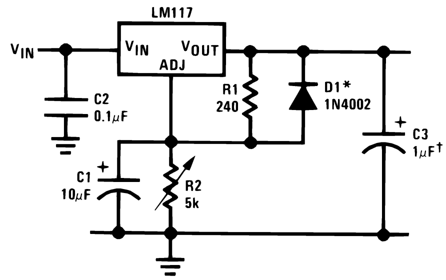


Figure 25. Adjustable Regulator with Improved Ripple Rejection



†Solid tantalum
*Discharges C1 if output is shorted to ground

Figure 26. High Stability 10V Regulator

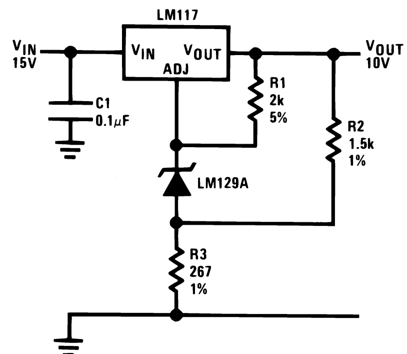
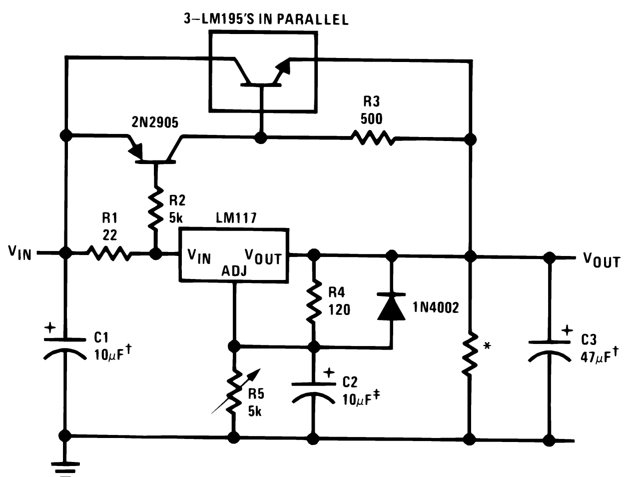
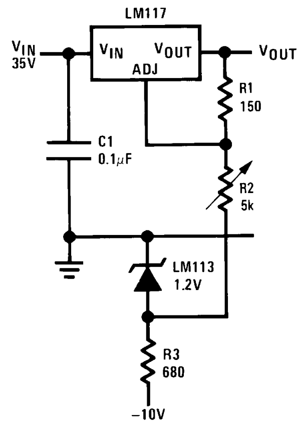


Figure 27. High Current Adjustable Regulator



‡Optional—improves ripple rejection
†Solid tantalum
*Minimum load current = 30 mA

Figure 28. 0 to 30V Regulator



Full output current not available at high input-output voltages

Figure 29. Power Follower

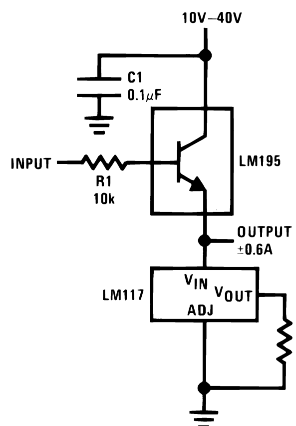
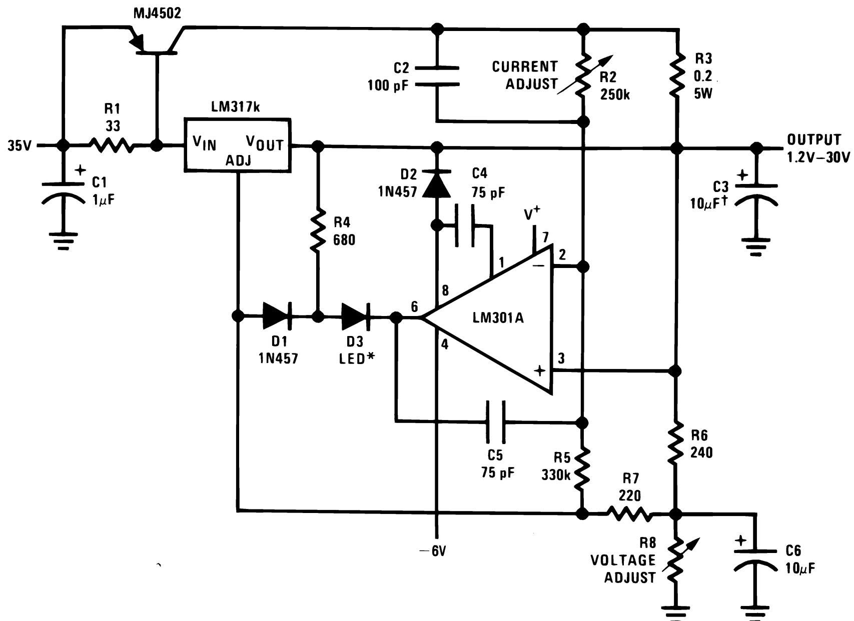


Figure 30. 5A Constant Voltage/Constant Current Regulator



†Solid tantalum

*Lights in constant current mode

Figure 31. 1A Current Regulator

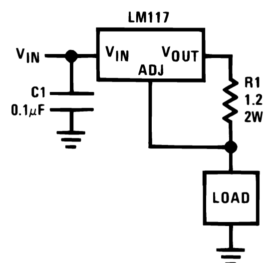
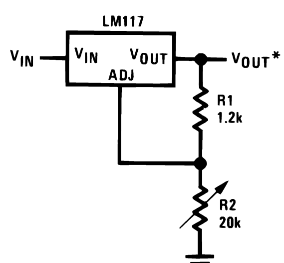


Figure 32. 1.2V–20V Regulator with Minimum Program Current



*Minimum load current ≅ 4 mA

Figure 33. High Gain Amplifier

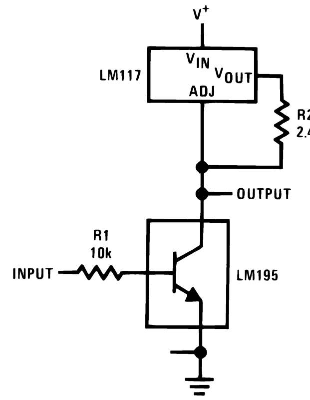
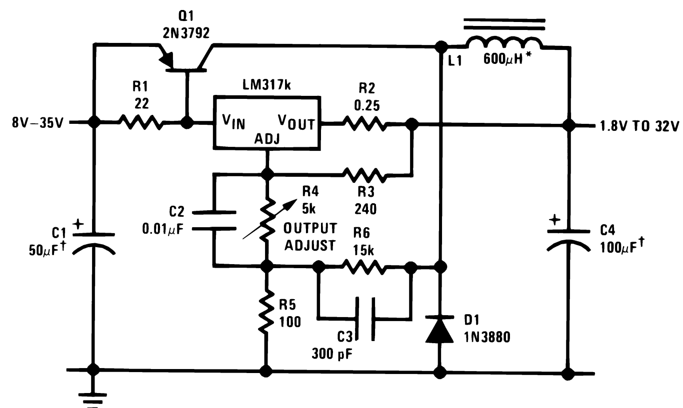
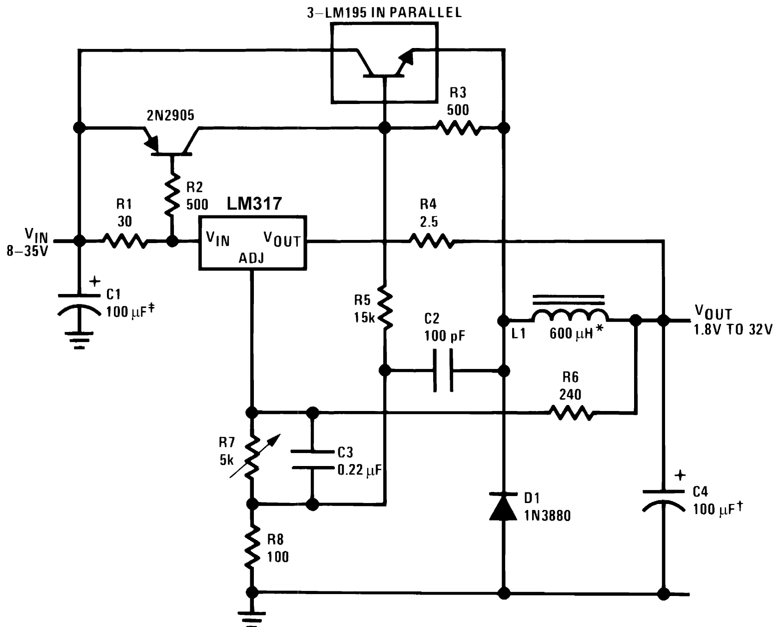


Figure 34. Low Cost 3A Switching Regulator



†Solid tantalum
*Core—Arnold A-254168-2 60 turns

Figure 35. 4A Switching Regulator with Overload Protection



†Solid tantalum
*Core—Arnold A-254168-2 60 turns

Figure 36. Precision Current Limiter

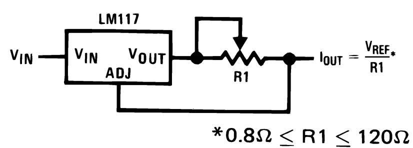


Figure 37. Tracking Preregulator

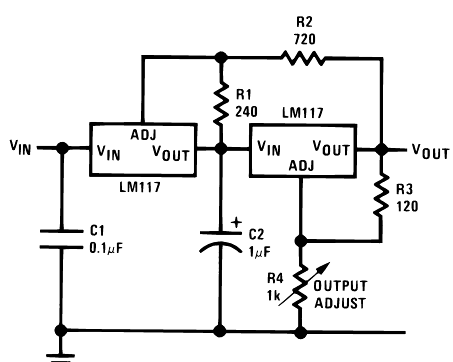
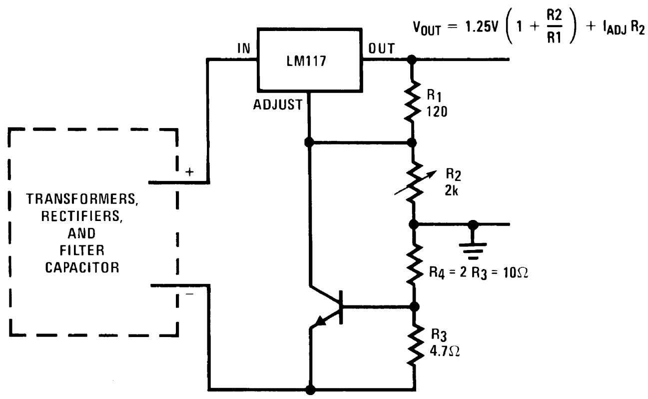


Figure 38. Current Limited Voltage Regulator

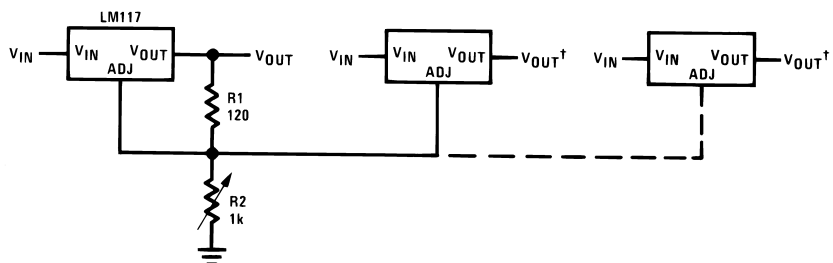


—Short circuit current is approximately $\frac{600 \text{ mV}}{R3}$, or 120 mA

(Compared to LM117's higher current limit)

—At 50 mA output only ¾ volt of drop occurs in R_3 and R_4

Figure 39. Adjusting Multiple On-Card Regulators with Single Control*



*All outputs within ±100 mV

†Minimum load—10 mA

Figure 40. AC Voltage Regulator

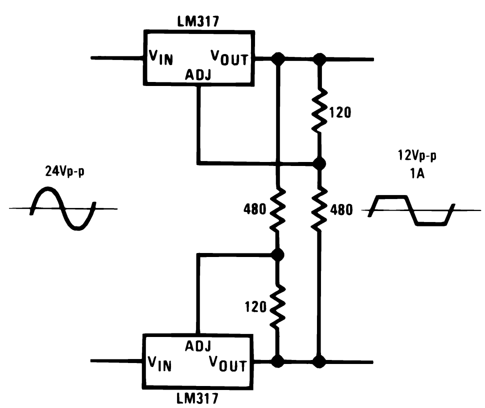
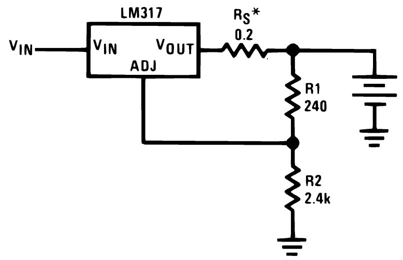


Figure 41. 12V Battery Charger



*R_S—sets output impedance of charger: $Z_{OUT} = R_S \left(1 + \frac{R2}{R1}\right)$

Use of R_S allows low charging rates with fully charged battery.

Figure 42. 50mA Constant Current Battery Charger

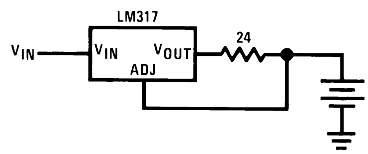


Figure 43. Adjustable 4A Regulator

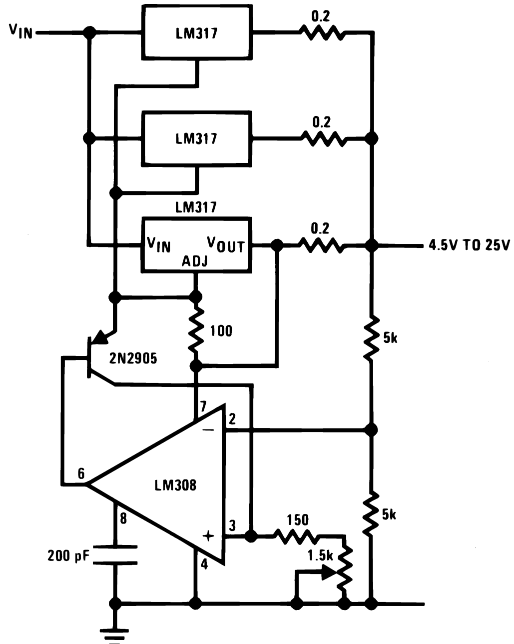
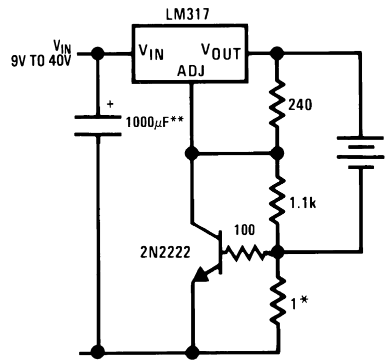
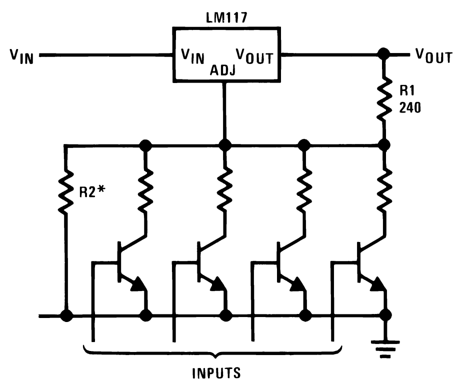


Figure 44. Current Limited 6V Charger



*Sets peak current (0.6A for 1Ω)
**The 1000μF is recommended to filter out input transients

Figure 45. Digitally Selected Outputs



*Sets maximum V_{OUT}

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
LM117GW/883	ACTIVE	CLGA	NAC	16	42	TBD	CU SNPB	Level-1-NA-UNLIM	
LM117H	ACTIVE	TO	NDT	3	500	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	
LM117H/NOPB	ACTIVE	TO	NDT	3	500	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	
LM117K	ACTIVE	TO-3	NDS	2	50	TBD	POST-PLATE	Level-1-NA-UNLIM	
LM117K STEEL	ACTIVE	TO-3	NDS	2	50	TBD	POST-PLATE	Level-1-NA-UNLIM	
LM117K STEEL/NOPB	ACTIVE	TO-3	NDS	2	50	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	
LM317AEMP	ACTIVE	SOT-223	DCY	4	1000	TBD	CU SNPB	Level-1-260C-UNLIM	
LM317AEMP/NOPB	ACTIVE	SOT-223	DCY	4	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
LM317AEMPX/NOPB	ACTIVE	SOT-223	DCY	4	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
LM317AH	ACTIVE	TO	NDT	3	500	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	
LM317AH/NOPB	ACTIVE	TO	NDT	3	500	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	
LM317AMDT	ACTIVE	PFM	NDP	3	75	TBD	CU SNPB	Level-1-235C-UNLIM	
LM317AMDT/NOPB	ACTIVE	PFM	NDP	3	75	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	
LM317AMDTX	ACTIVE	PFM	NDP	3	2500	TBD	CU SNPB	Level-1-235C-UNLIM	
LM317AMDTX/NOPB	ACTIVE	PFM	NDP	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	
LM317AT	ACTIVE	TO-220	NDE	3	45	TBD	CU SNPB	Level-1-NA-UNLIM	
LM317AT/NOPB	ACTIVE	TO-220	NDE	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-1-NA-UNLIM	
LM317EMP	ACTIVE	SOT-223	DCY	4	1000	TBD	CU SNPB	Level-1-260C-UNLIM	
LM317EMP/NOPB	ACTIVE	SOT-223	DCY	4	1000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
LM317EMPX/NOPB	ACTIVE	SOT-223	DCY	4	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
LM317H	ACTIVE	TO	NDT	3	500	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	
LM317H/NOPB	ACTIVE	TO	NDT	3	500	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	
LM317K STEEL	ACTIVE	TO-3	NDS	2	50	TBD	POST-PLATE	Level-1-NA-UNLIM	
LM317K STEEL/NOPB	ACTIVE	TO-3	NDS	2	50	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	
LM317MDT/NOPB	ACTIVE	PFM	NDP	3	75	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	
LM317MDTX/NOPB	ACTIVE	PFM	NDP	3	2500	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	
LM317S/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	
LM317SX/NOPB	ACTIVE	DDPAK/ TO-263	KTT	3	500	Pb-Free (RoHS Exempt)	CU SN	Level-3-245C-168 HR	
LM317T	ACTIVE	TO-220	NDE	3	45	TBD	CU SNPB	Level-1-NA-UNLIM	
LM317T/LF01	ACTIVE	TO-220	NDG	3	45	Pb-Free (RoHS Exempt)	CU SN	Level-4-260C-72 HR	
LM317T/NOPB	ACTIVE	TO-220	NDE	3	45	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

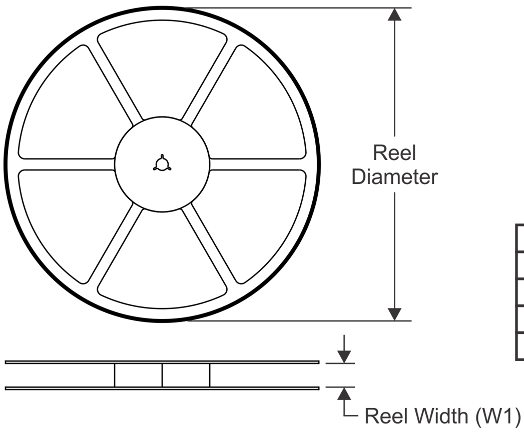
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

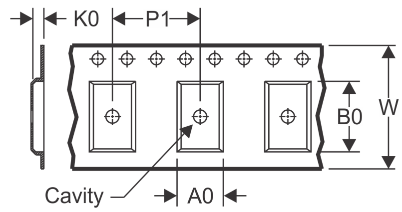
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

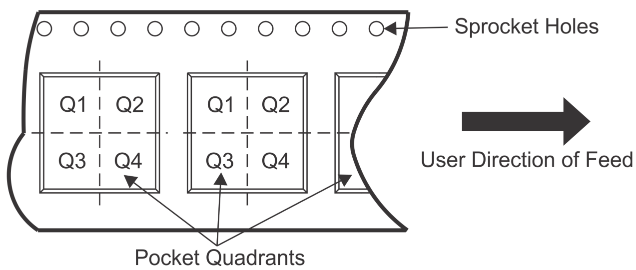


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

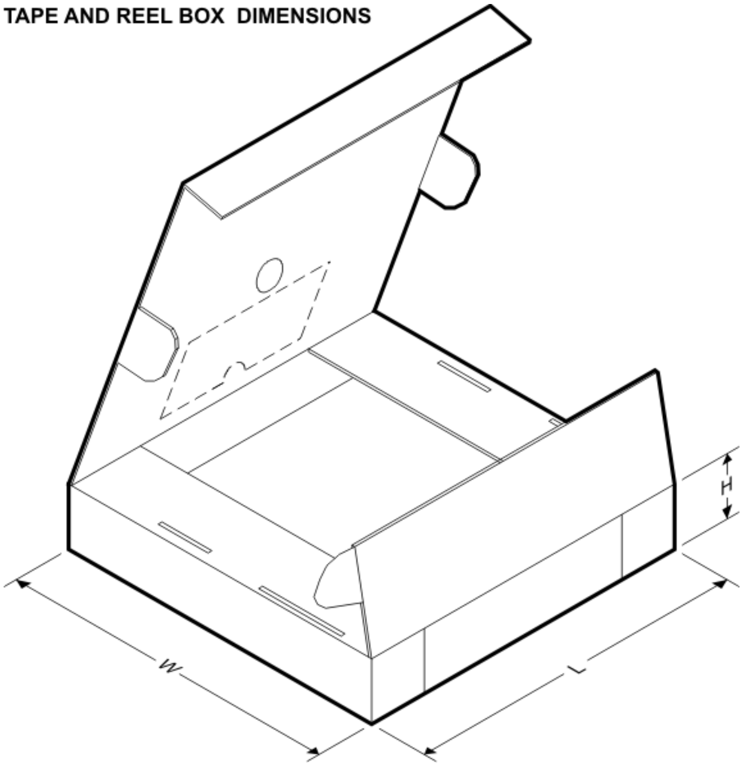
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM317AEMP	SOT-223	DCY	4	1000	330.0	16.4	7.0	7.5	2.2	12.0	16.0	Q3
LM317AEMP/NOPB	SOT-223	DCY	4	1000	330.0	16.4	7.0	7.5	2.2	12.0	16.0	Q3
LM317AEMPX/NOPB	SOT-223	DCY	4	2000	330.0	16.4	7.0	7.5	2.2	12.0	16.0	Q3
LM317AMDTX	PFM	NDP	3	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2
LM317AMDTX/NOPB	PFM	NDP	3	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2
LM317EMP	SOT-223	DCY	4	1000	330.0	16.4	7.0	7.5	2.2	12.0	16.0	Q3
LM317EMP/NOPB	SOT-223	DCY	4	1000	330.0	16.4	7.0	7.5	2.2	12.0	16.0	Q3
LM317EMPX/NOPB	SOT-223	DCY	4	2000	330.0	16.4	7.0	7.5	2.2	12.0	16.0	Q3
LM317MDTX/NOPB	PFM	NDP	3	2500	330.0	16.4	6.9	10.5	2.7	8.0	16.0	Q2
LM317SX/NOPB	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.75	14.85	5.0	16.0	24.0	Q2

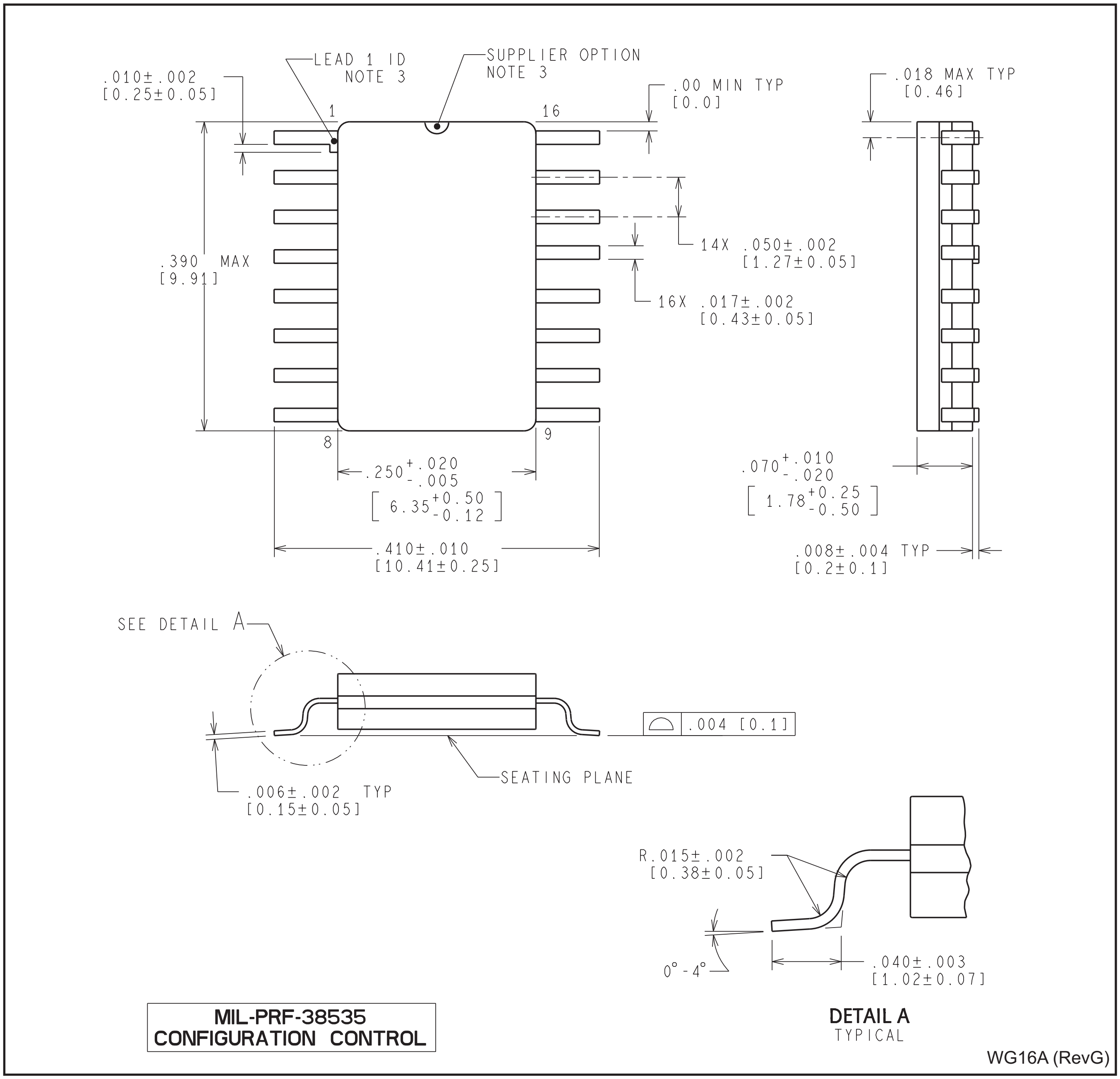
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

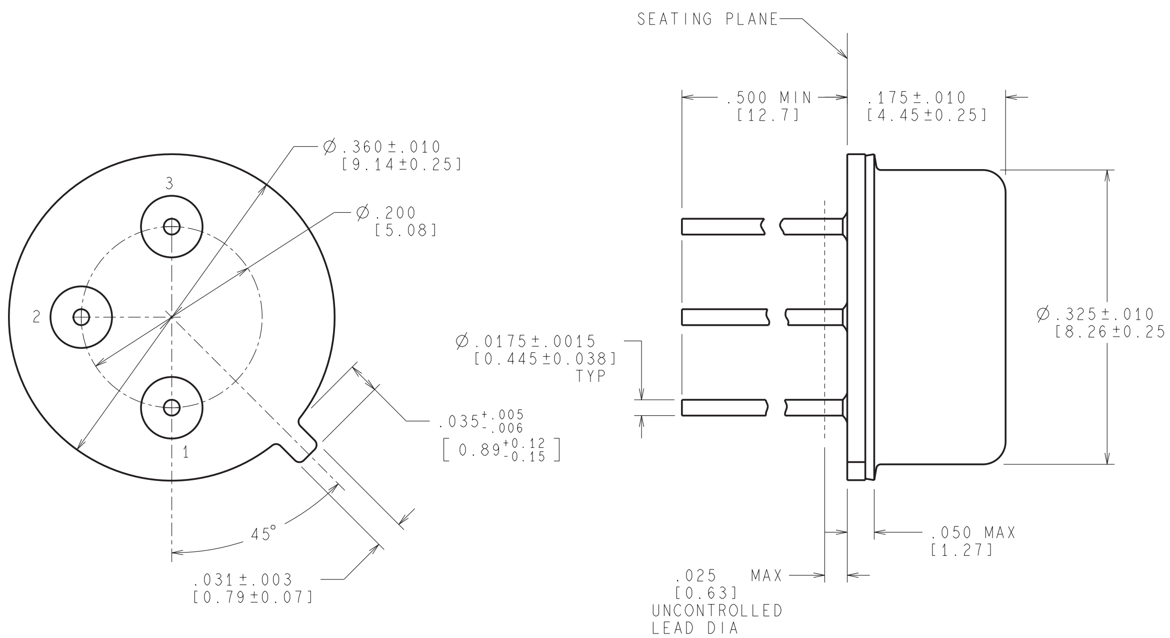
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM317AEMP	SOT-223	DCY	4	1000	349.0	337.0	45.0
LM317AEMP/NOPB	SOT-223	DCY	4	1000	349.0	337.0	45.0
LM317AEMPX/NOPB	SOT-223	DCY	4	2000	354.0	340.0	35.0
LM317AMDTX	PFM	NDP	3	2500	354.0	340.0	35.0
LM317AMDTX/NOPB	PFM	NDP	3	2500	358.0	343.0	63.0
LM317EMP	SOT-223	DCY	4	1000	349.0	337.0	45.0
LM317EMP/NOPB	SOT-223	DCY	4	1000	349.0	337.0	45.0
LM317EMPX/NOPB	SOT-223	DCY	4	2000	354.0	340.0	35.0
LM317MDTX/NOPB	PFM	NDP	3	2500	358.0	343.0	63.0
LM317SX/NOPB	DDPAK/TO-263	KTT	3	500	358.0	343.0	63.0

NAC0016A



LEAD 1 ID
NOTE 3
SUPPLIER OPTION
NOTE 3
.010±.002
[0.25±0.05]
1
16
.00 MIN TYP
[0.0]
.018 MAX TYP
[0.46]
14X .050±.002
[1.27±0.05]
.390 MAX
[9.91]
16X .017±.002
[0.43±0.05]
8
9
.250 +.020 -.005
[6.35 +0.50 -0.12]
.070 +.010 -.020
[1.78 +0.25 -0.50]
.410±.010
[10.41±0.25]
.008±.004 TYP
[0.2±0.1]
SEE DETAIL A
.004 [0.1]
SEATING PLANE
.006±.002 TYP
[0.15±0.05]
R.015±.002
[0.38±0.05]
0°-4°
.040±.003
[1.02±0.07]
MIL-PRF-38535
CONFIGURATION CONTROL
DETAIL A
TYPICAL
WG16A (RevG)

NDT0003A

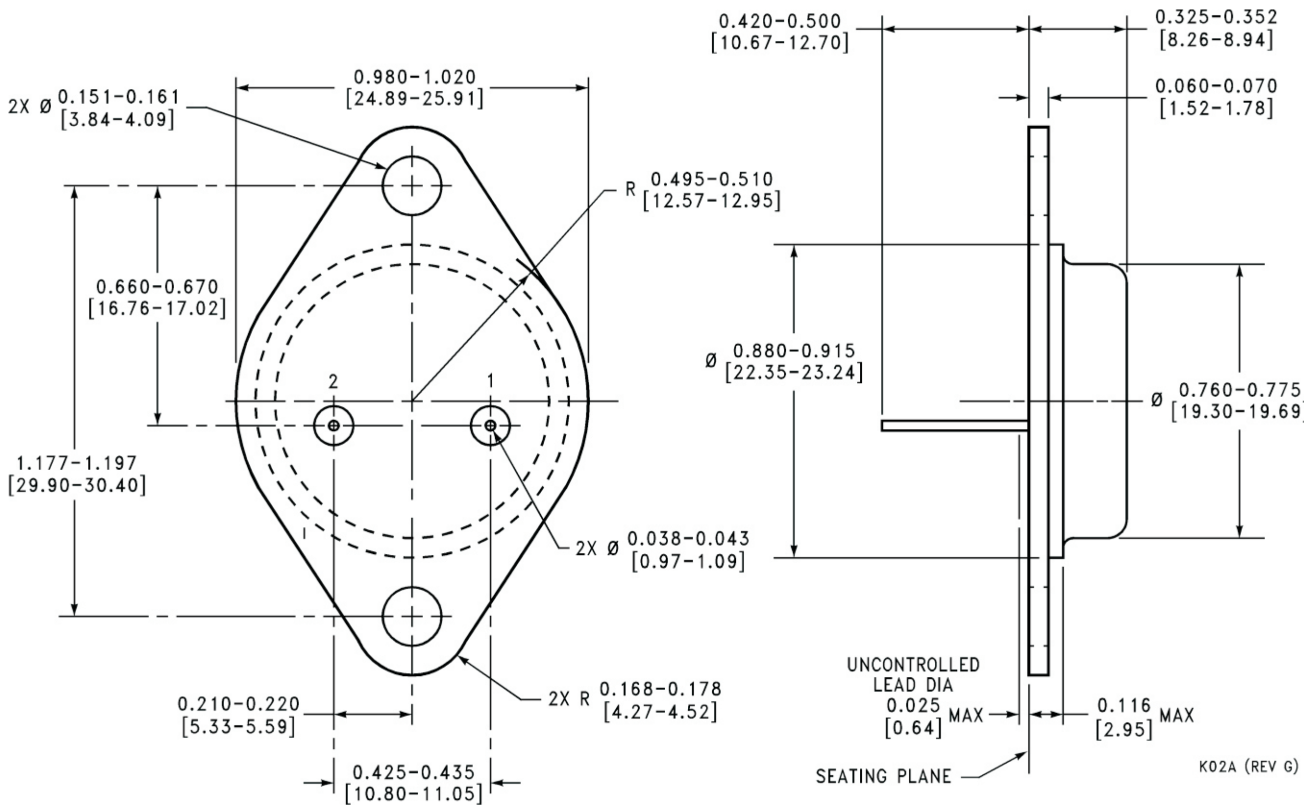


CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS

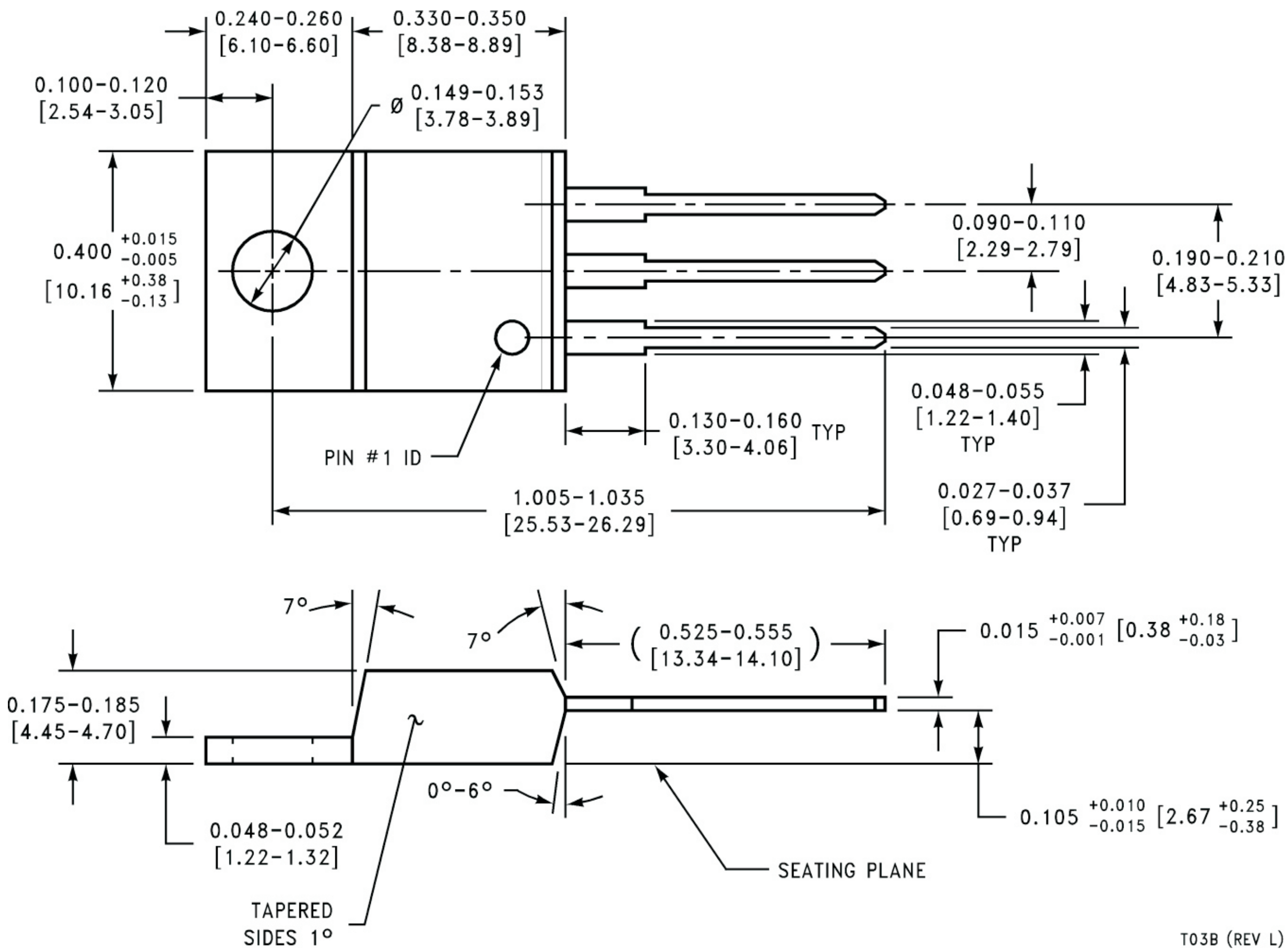
MIL-PRF-38535
CONFIGURATION CONTROL

H03A (Rev D)

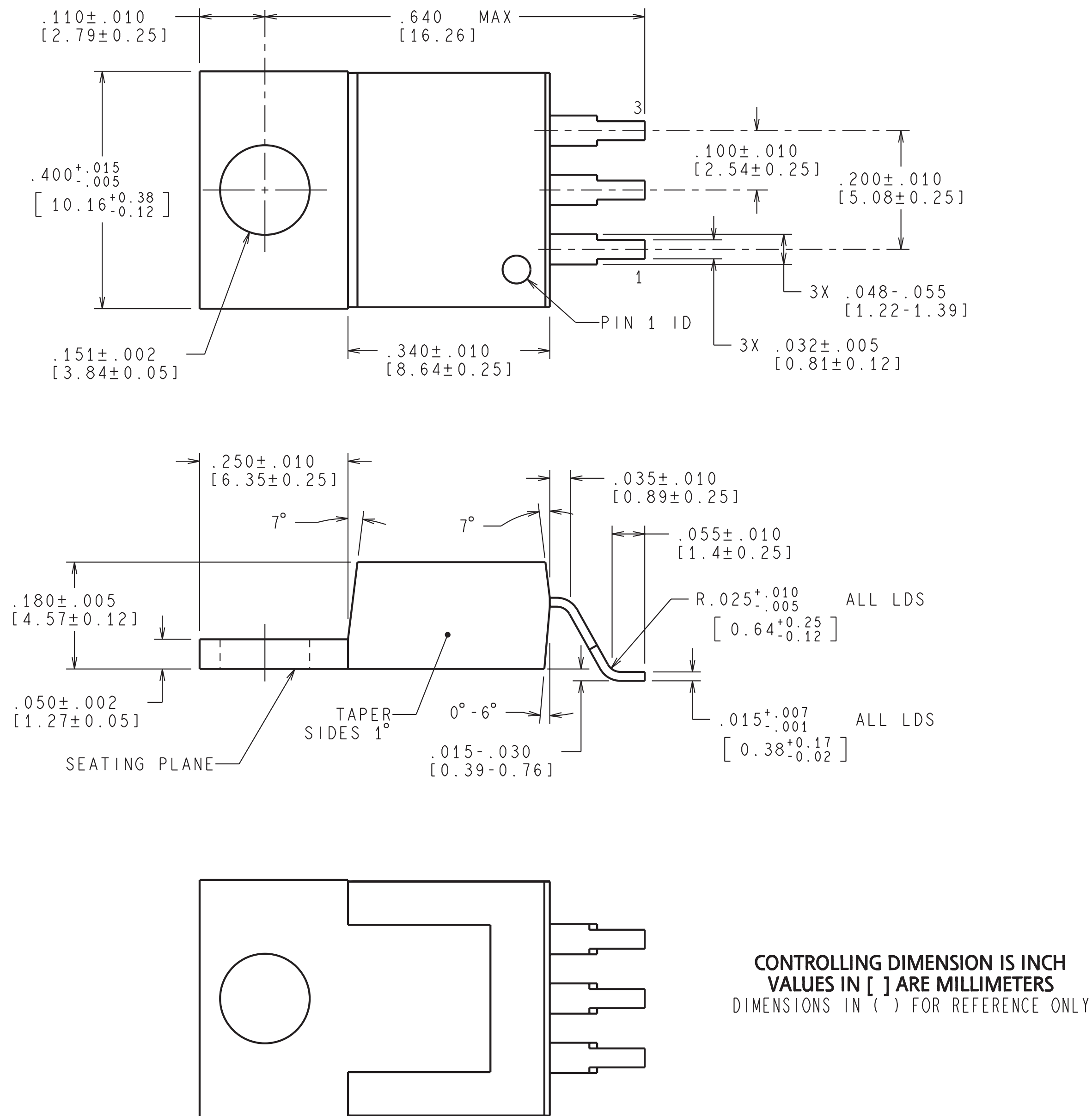
NDS0002A


0.980–1.020
[24.89–25.91]
2X Ø 0.151–0.161
[3.84–4.09]
R 0.495–0.510
[12.57–12.95]
0.660–0.670
[16.76–17.02]
2
1
1.177–1.197
[29.90–30.40]
2X Ø 0.038–0.043
[0.97–1.09]
2X R 0.168–0.178
[4.27–4.52]
0.210–0.220
[5.33–5.59]
0.425–0.435
[10.80–11.05]
0.420–0.500
[10.67–12.70]
0.325–0.352
[8.26–8.94]
0.060–0.070
[1.52–1.78]
Ø 0.880–0.915
[22.35–23.24]
Ø 0.760–0.775
[19.30–19.69]
UNCONTROLLED
LEAD DIA
0.025
[0.64] MAX
0.116
[2.95] MAX
SEATING PLANE
K02A (REV G)

NDE0003B

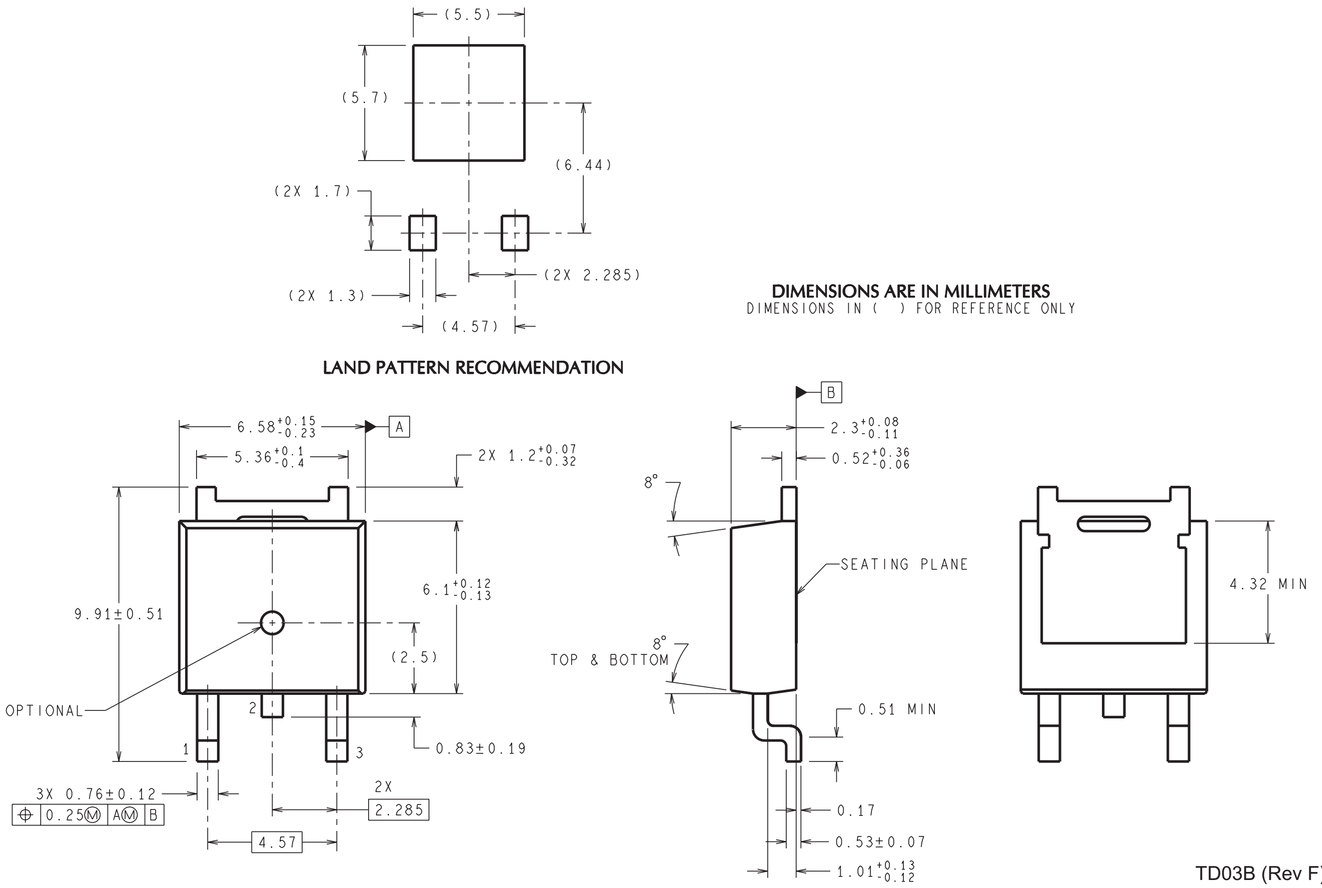

0.240-0.260
[6.10-6.60]
0.330-0.350
[8.38-8.89]
0.100-0.120
[2.54-3.05]
Ø 0.149-0.153
[3.78-3.89]
0.400 +0.015 -0.005
[10.16 +0.38 -0.13]
0.090-0.110
[2.29-2.79]
0.190-0.210
[4.83-5.33]
0.048-0.055
[1.22-1.40]
TYP
0.130-0.160 TYP
[3.30-4.06]
PIN #1 ID
1.005-1.035
[25.53-26.29]
0.027-0.037
[0.69-0.94]
TYP
7°
7°
(0.525-0.555
[13.34-14.10])
0.015 +0.007 -0.001 [0.38 +0.18 -0.03]
0.175-0.185
[4.45-4.70]
0°-6°
0.048-0.052
[1.22-1.32]
0.105 +0.010 -0.015 [2.67 +0.25 -0.38]
SEATING PLANE
TAPERED
SIDES 1°
T03B (REV L)

NDG0003F



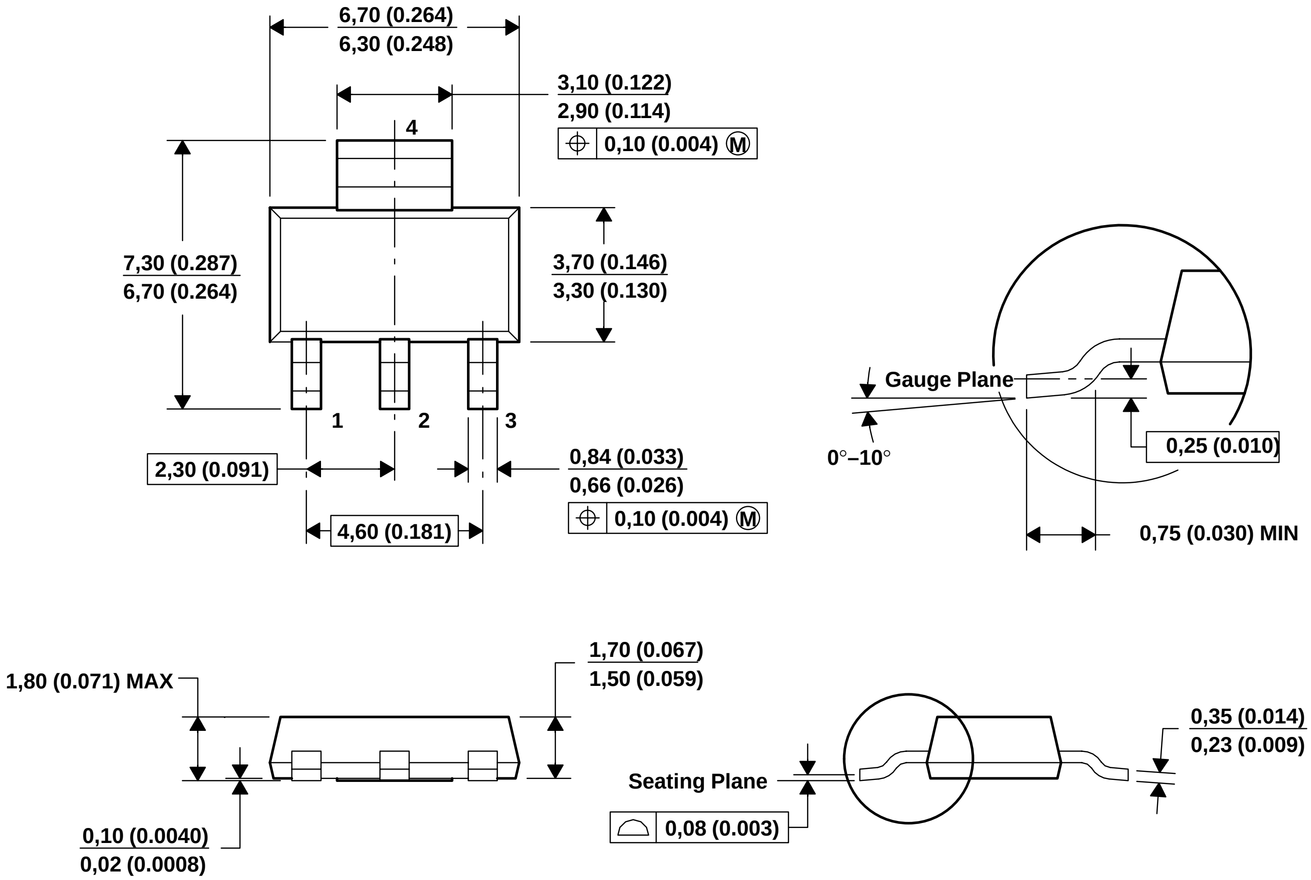
T03F (Rev B)

NDP0003B



TD03B (Rev F)

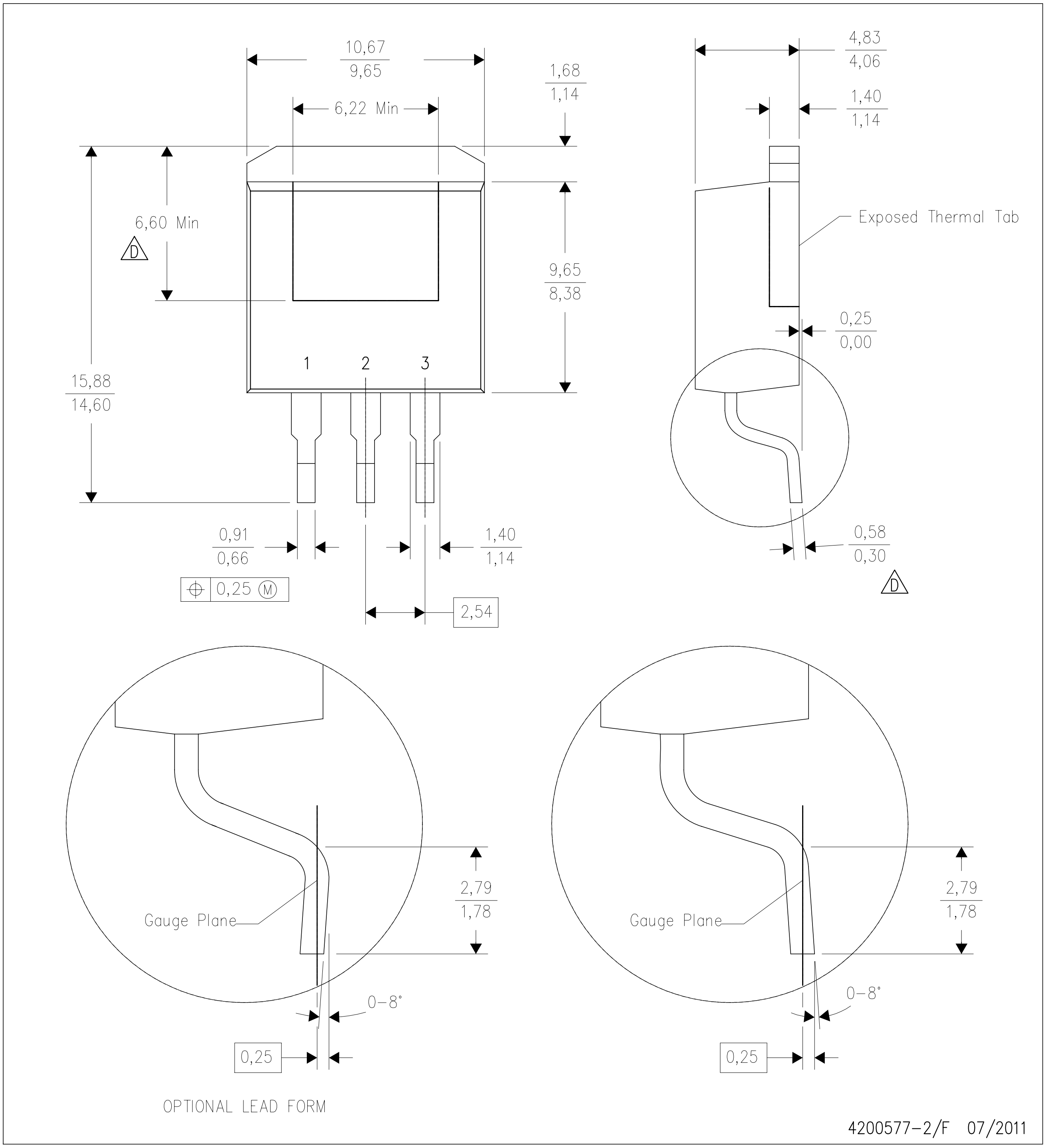
DCY (R-PDSO-G4) **PLASTIC SMALL-OUTLINE**



4202506/B 06/2002

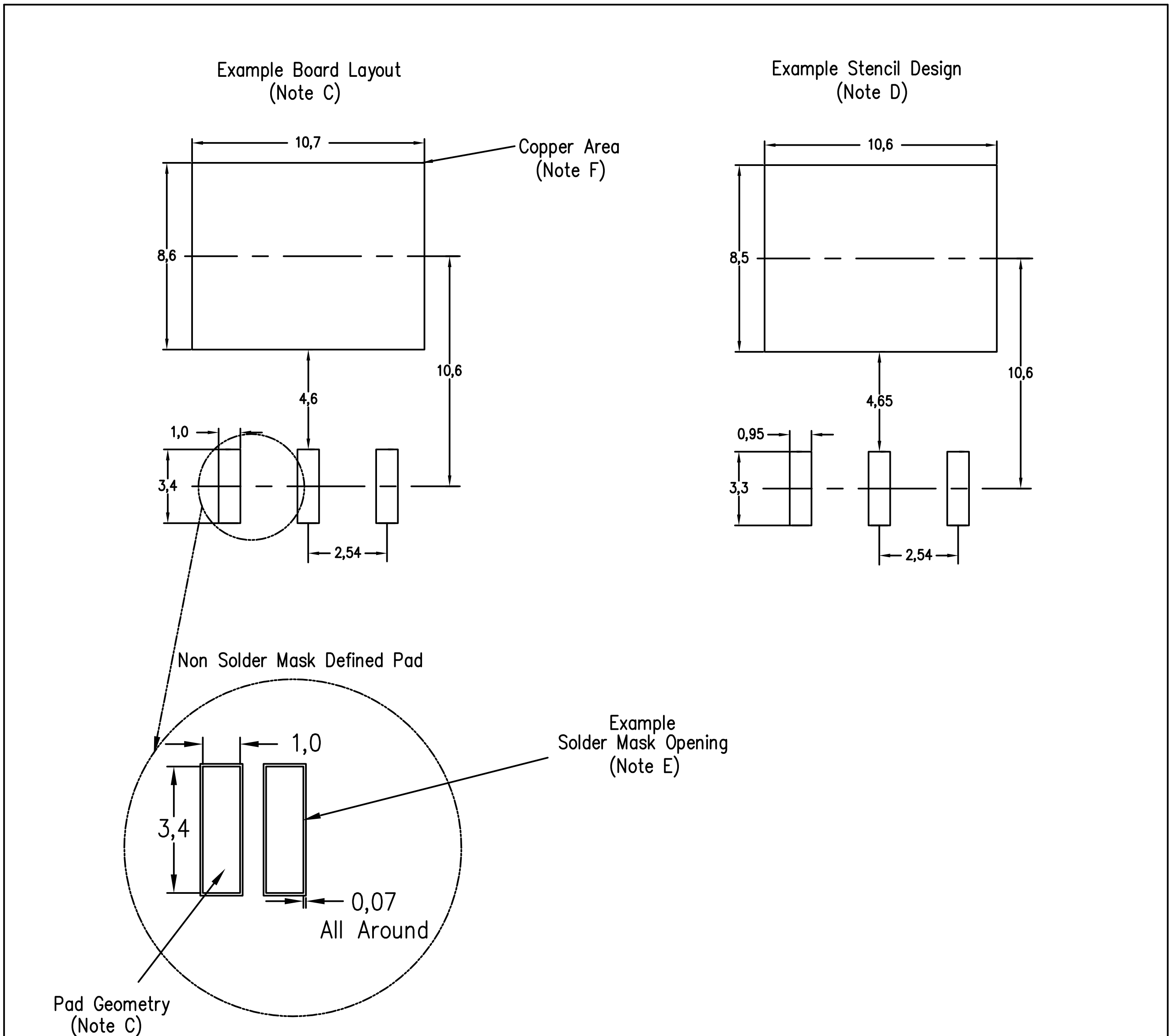
NOTES: A. All linear dimensions are in millimeters (inches).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion.
D. Falls within JEDEC TO-261 Variation AA.

KTT (R–PSFM–G3) PLASTIC FLANGE–MOUNT PACKAGE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash or protrusion not to exceed 0.005 (0,13) per side.
D. Falls within JEDEC TO–263 variation AA, except minimum lead thickness and minimum exposed pad length.

KTT (R–PSFM–G3) PLASTIC FLANGE–MOUNT PACKAGE



4208208–2/C 08/12

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–SM–782 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.
F. This package is designed to be soldered to a thermal pad on the board. Refer to the Product Datasheet for specific thermal information, via requirements, and recommended thermal pad size. For thermal pad sizes larger than shown a solder mask defined pad is recommended in order to maintain the solderable pad geometry while increasing copper area.